Title (en)

Electroplating of nickel on nickel ferrite devices

Title (de)

Elektroplattieren von Nickel auf Nickel-Ferrit Vorrichtungen

Title (fr)

Dépôt électrolytique de nickel sur des dispositifs en nickel ferrite

Publication

EP 0785296 B1 20000315 (EN)

Application

EP 96309396 A 19961223

Priority

- US 58107995 A 19951229
- US 76918996 A 19961218

Abstract (en)

[origin: EP0785296A1] This invention is predicated on the discovery by the present applicants that boric acid in conventional nickel plating baths is responsible for excessive lateral growth in the electroplating of nickel on nickel ferrite substrates. While nickel baths without boric acid do not yield acceptable electrodeposits, the boric acid interacts with the ferrite substrate to cause excessive lateral growth. Applicants further discovered that by eliminating the boric acid and adding another acidic plating buffer such as citric acid, one can obtain isotropic nickel plating and produce a wire-bondable surface.

IPC 1-7

C25D 3/12

IPC 8 full level

C25D 5/18 (2006.01); **C25D 3/12** (2006.01); **C25D 5/26** (2006.01)

CPC (source: EP)

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Cited by

CN111636077A; CN105529132A; EP3933072A1; US11054199B2; US11835307B2; US10297377B2; US10804021B2; WO2018234229A1

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